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Jameco Part Number 35799

T-75-37-07

Z8530 Military SCC Serial Communications Controller

Zilog

Military Electrical Specification

July 1985

FEATURES

- Two independent, 0 to 1.5M bit/second, full-duplex channels, each with a separate crystal oscillator, baud rate generator, and Digital Phase-Locked Loop for clock recovery.
- Multi-protocol operation under program control; programmable for NRZ, NRZI, or FM data encoding.
- Asynchronous mode with five to eight bits and one, one and one-half, or two stop bits per character; programmable clock factor; break detection and generation; parity, overrun, and framing error detection.
- Synchronous mode with internal or external character synchronization on one or two synchronous characters and CRC generation and checking with CRC-16 or CRC-CCITT preset to either 1s or 0s.
- SDLC/HDLC mode with comprehensive frame-level control, automatic zero insertion and deletion, I-field residue handling, abort generation and detection, CRC generation and checking, and SDLC Loop mode operation.
- Local Loopback and Auto Echo modes.
- 1.544M bit/second T1 digital trunk compatible version available.

GENERAL DESCRIPTION

The Z8530 SCC Serial Communications Controller is a dual-channel, multi-protocol data communications peripheral designed for use with conventional non-multiplexed buses. The SCC functions as a serial-to-parallel, parallel-to-serial converter/controller. The SCC can be software-configured to satisfy a wide variety of serial communications applications. The device contains a variety of new, sophisticated internal functions including on-chip baud rate generators, Digital Phase-Locked Loops, and crystal oscillators that dramatically reduce the need for external logic.

The SCC handles Asynchronous formats, Synchronous byte-oriented protocols such as IBM Bisync, and Synchronous bit-oriented protocols such as HDLC and IBM SDLC. This versatile device supports virtually any serial data transfer application (cassette, diskette, tape drives, etc.).

The device can generate and check CRC codes in any Synchronous mode and can be programmed to check data integrity in various modes. The SCC also has facilities for modem controls in both channels. In applications where these controls are not needed, the modem controls can be used for general-purpose I/O.

The Z-BUS daisy-chain interrupt hierarchy is also supported—as is standard for Zilog peripheral components.

TIMING

The SCC generates internal control signals from $\overline{WR}$ and $\overline{RD}$ that are related to PCLK. Since PCLK has no phase relationship with $\overline{WR}$ and $\overline{RD}$, the circuitry generating these internal control signals must provide time for metastable conditions to disappear. This gives rise to a recovery time related to PCLK. The recovery time applies only between bus transactions involving the SCC. The recovery time required for proper operation is specified from the rising edge of $\overline{WR}$ or $\overline{RD}$ in the first transaction involving the SCC to the falling edge of $\overline{WR}$ or $\overline{RD}$ in the second transaction involving the SCC. This time must be at least 6 PCLK cycles plus 200 ns.

Read Cycle Timing. Figure 1 illustrates Read cycle timing. Addresses on A/$\overline{B}$ and D/$\overline{C}$ and the status on $\overline{INTACK}$ must remain stable throughout the cycle. If $\overline{CE}$ falls after $\overline{RD}$ falls or if it rises before $\overline{RD}$ rises, the effective $\overline{RD}$ is shortened.

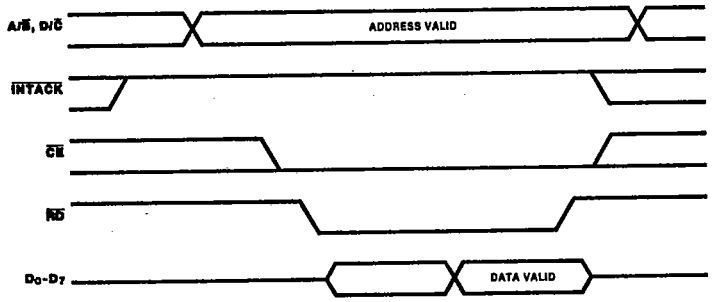


Figure 1. Read Cycle Timing

Write Cycle Timing. Figure 2 illustrates Write cycle timing. Addresses on A/$\overline{B}$ and D/$\overline{C}$ and the status on $\overline{INTACK}$ must remain stable throughout the cycle. If $\overline{CE}$ falls after $\overline{WR}$ falls or if it rises before $\overline{WR}$ rises, the effective $\overline{WR}$ is shortened.

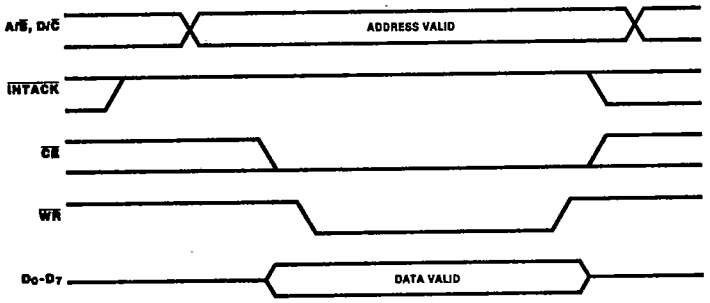


Figure 2. Write Cycle Timing

Interrupt Acknowledge Cycle Timing. Figure 3 illustrates Interrupt Acknowledge cycle timing. Between the time $\overline{INTACK}$ goes Low and the falling edge of $\overline{RD}$, the internal and external IEI/IEO daisy chains settle. If there is an interrupt pending in the SCC and IEI is High when $\overline{RD}$ falls, the Acknowledge cycle is intended for the SCC. In this case, the SCC may be programmed to respond to $\overline{RD}$ Low by placing its interrupt vector on D_0-D_7 and it then sets the appropriate Interrupt-Under-Service latch internally.

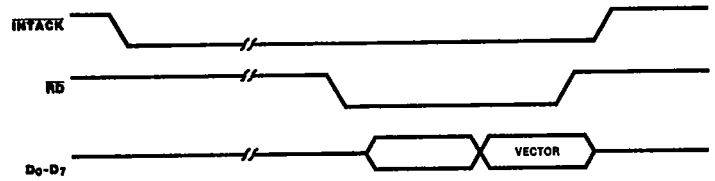


Figure 3. Interrupt Acknowledge Cycle Timing

2023-003, 004, 005

ABSOLUTE MAXIMUM RATINGS

Guaranteed by characterization/design.

Voltages on all pins with respect to GND ..... −0.3V to +7V
Operating Case Temperature ..... −55°C to +125°C
Storage Temperature Range ..... −65°C to +150°C
Absolute Maximum Power Dissipation 2.0W

Stresses greater than those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

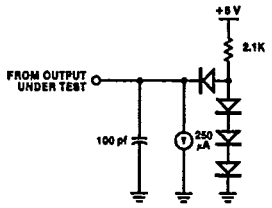
STANDARD TEST CONDITIONS

The DC Characteristics and Capacitance sections listed below apply for the following standard test conditions, unless otherwise noted. All voltages are referenced to GND. Positive current flows into the referenced pin.

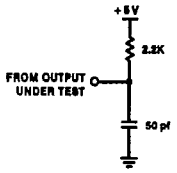
Military Operating Temperature Range (T_C)
−55°C to +125°C

Standard Military Test Condition
$+4.5V \leq V_{CC} \leq +5.5V$

All AC parameters assume a load capacitance of 50 pf. Add 15 ns delay for each 50 pf increase in load up to a maximum of 200 pf for the data bus. AC timing measurements are referenced to 1.5 volts (except for clock, which is referenced to the 20% and 80% points).



Standard Test Load



Open-Drain Test Load

DC CHARACTERISTICS

Symbol	Parameter	Min	Max	Unit	Condition
V_{IH}	Input High Voltage	2.2[a]	$V_{CC}+0.3$[c]	V	
V_{IL}	Input Low Voltage	−0.3[c]	0.8[a]	V	
V_{OH}	Output High Voltage	2.4[c]		V	$I_{OH} = -250\,\mu A$
V_{OL}	Output Low Voltage		0.4[c]	V	$I_{OL} = +2.0$ mA
I_{IL}	Input Leakage		±10[a]	µA	$0.4 \leq V_{IN} \leq +2.4V$
I_{OL}	Output Leakage		±10[a]	µA	$0.4 \leq V_{OUT} \leq +2.4V$
I_{CC}	V_{CC} Supply Current		350[a]	mA	

V_{CC} = 5V ± 5% unless otherwise specified, over specified temperature range.

CAPACITANCE

Symbol	Parameter	Min	Max	Unit
C_{IN}	Input Capacitance		10[c]	pf
C_{OUT}	Output Capacitance		15[c]	pf
$C_{I/O}$	Bidirectional Capacitance		20[c]	pf

f = 1 MHz, over specified temperature range.
Unmeasured pins returned to ground.

Parameter Test Status:

[a] Tested
[b] Guaranteed
[c] Guaranteed by Characterization/Design

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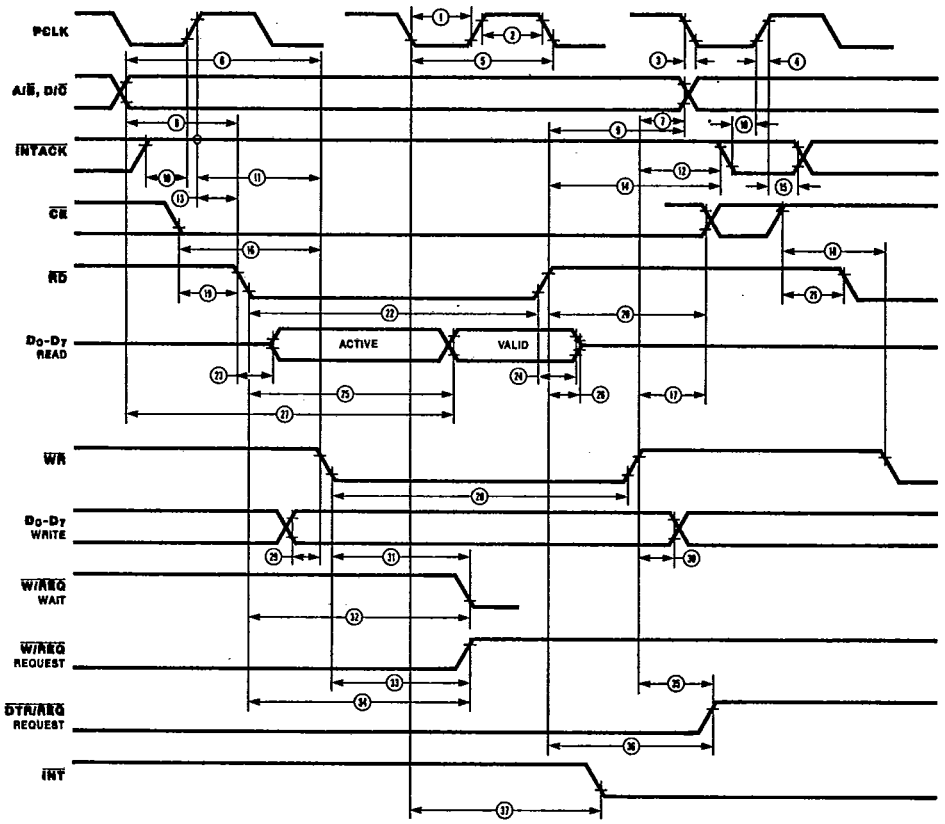
READ AND WRITE TIMING



AC CHARACTERISTICS

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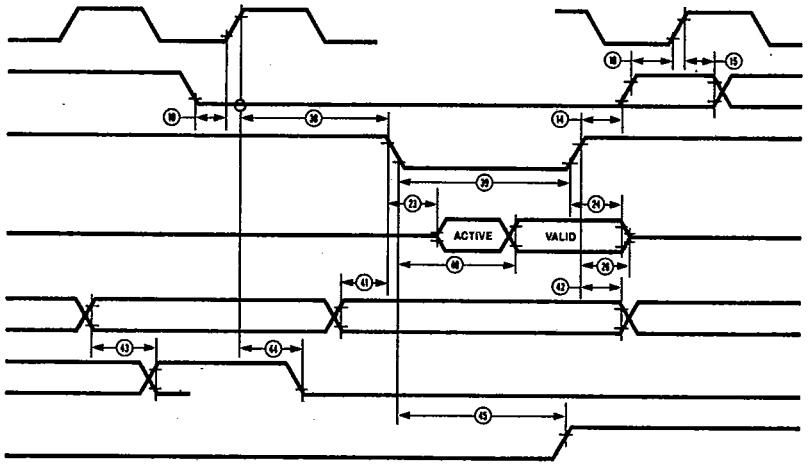
Number	Symbol	Parameter	4 MHz Min	4 MHz Max	6 MHz Min	6 MHz Max	Notes†
1	TwPCl	PCLK Low Width	105[b]	2000[b]	70[a]	1000[b]	
2	TwPCh	PCLK High Width	105[b]	2000[b]	70[a]	1000[b]	
3	TfPC	PCLK Fall Time		20[b]		10[a]	
4	TrPC	PCLK Rise Time		20[b]		10[a]	
5	TcPC	PCLK Cycle Time	250[a]	4000[b]	165[a]	2000[b]	
6	TsA(WR)	Address to $\overline{WR}$ ↓ Setup Time	80[a]		80[a]		
7	ThA(WR)	Address to $\overline{WR}$ ↑ Hold Time	0[b]		0[b]		
8	TsA(RD)	Address to $\overline{RD}$ ↓ Setup Time	80[a]		80[a]		
9	ThA(RD)	Address to $\overline{RD}$ ↑ Hold Time	0[b]		0[b]		
10	TsIA(PC)	$\overline{INTACK}$ to PCLK ↑ Setup time	0[a]		0[a]		1
11	TsIAi(WR)	$\overline{INTACK}$ to $\overline{WR}$ ↓ Setup Time	200[b]		160[b]		2
12	ThIA(WR)	$\overline{INTACK}$ to $\overline{WR}$ ↑ Hold Time	0[b]		0[b]		
13	TsIAi(RD)	$\overline{INTACK}$ to $\overline{RD}$ ↓ Setup Time	200[b]		160[b]		2
14	ThIA(RD)	$\overline{INTACK}$ to $\overline{RD}$ ↑ Hold Time	0[b]		0[a]		1
15	ThIA(PC)	$\overline{INTACK}$ to PCLK ↑ Hold Time	100[b]		100[b]		
16	TsCEl(WR)	$\overline{CE}$ Low to $\overline{WR}$ ↓ Setup Time	0[a]		0[b]		
17	ThCE(WR)	$\overline{CE}$ to $\overline{WR}$ ↑ Hold Time	0[a]		0[a]		
18	TsCEh(WR)	$\overline{CE}$ High to $\overline{WR}$ ↓ Setup Time	100[b]		70[b]		
19	TsCEl(RD)	$\overline{CE}$ Low to $\overline{RD}$ ↓ Setup Time	0[a]		0[b]		2
20	ThCE(RD)	$\overline{CE}$ to $\overline{RD}$ ↑ Hold Time	0[a]		0[a]		2
21	TsCEh(RD)	$\overline{CE}$ High to $\overline{RD}$ ↓ Setup Time	100[a]		70[b]		2
22	TwRDl	$\overline{RD}$ Low Width	390[a]		250[b]		2
23	TdRD(DRA)	$\overline{RD}$ ↓ to Read Data Active Delay	0[a]		0[b]		
24	TdRDr(DR)	$\overline{RD}$ ↑ to Read Data Not Valid Delay	0[a]		0[b]		
25	TdRDf(DR)	$\overline{RD}$ ↓ to Read Data Valid Delay		250[a]		180[a]	
26	TdRD(DRz)	$\overline{RD}$ ↑ to Read Data Float Delay		70[a]		45[b]	3

NOTES:
1. Tested in Interrupt Acknowledge Cycle only.
2. Parameter does not apply to Interrupt Acknowledge transactions.
3. Float delay is defined as the time required for a ±0.5V change in the output with a maximum DC load and minimum AC load.
† Units in nanoseconds (ns).

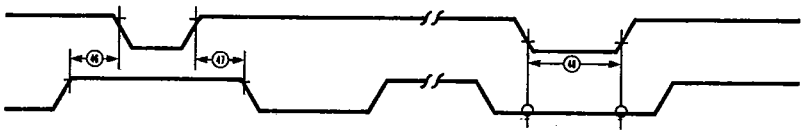
Parameter Test Status:

[a] Tested
[b] Guaranteed
[c] Guaranteed by Characterization/Design

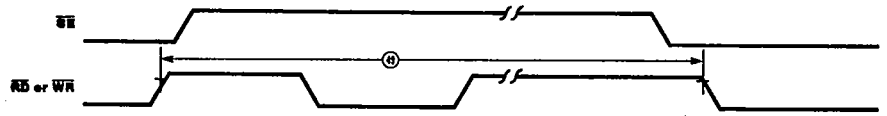
INTERRUPT ACKNOWLEDGE TIMING



RESET TIMING



CYCLE TIMING



AC CHARACTERISTICS

T-75-37-07

Number	Symbol	Parameter	4 MHz Min	4 MHz Max	6 MHz Min	6 MHz Max	Notes†
27	TdA(DR)	Address Required Valid to Read Data Valid Delay		590[a]		420[a]	
28	TwWRl	$\overline{WR}$ Low Width	390[b]		250[b]		
29	TsDW(WR)	Write Data to $\overline{WR}$ ↓ Setup Time	0[b]		0[b]		
30	ThDW(WR)	Write Data to $\overline{WR}$ ↑ Hold Time	0[a]		0[a]		
31	TdWR(W)	$\overline{WR}$ ↓ to Wait Valid Delay		240[b]		200[b]	5
32	TdRD(W)	$\overline{RD}$ ↓ to Wait Valid Delay		240[b]		200[b]	5
33	TdWRf(REQ)	$\overline{WR}$ ↓ to W/$\overline{REQ}$ Not Valid Delay		240[b]		200[b]	
34	TdRDf(REQ)	$\overline{RD}$ ↓ to W/$\overline{REQ}$ Not Valid Delay		240[b]		200[b]	
35	TdWRr(REQ)	$\overline{WR}$ ↑ to $\overline{DTR}$/$\overline{REQ}$ Not Valid Delay		5TcPC +300[b]		5TcPC +250[b]	
36	TdRDr(REQ)	$\overline{RD}$ ↑ to $\overline{DTR}$/$\overline{REQ}$ Not Valid Delay		5TcPC +300[b]		5TcPC +250[b]	
37	TdPC(INT)	PCLK ↓ to $\overline{INT}$ Valid Delay		500[b]		500[b]	5
38	TdIAi(RD)	$\overline{INTACK}$ to $\overline{RD}$ ↓ (Acknowledge) Delay	250[b]		250[b]		6
39	TwRDA	$\overline{RD}$ (Acknowledge) Width	285[b]		250[b]		
40	TdRDA(DR)	$\overline{RD}$ ↓ (Acknowledge) to Read Data Valid Delay		190[b]		180[a]	
41	TsIEI(RDA)	IEI to $\overline{RD}$ ↓ (Acknowledge) Setup Time	120[b]		100[b]		
42	ThIEI(RDA)	IEI to $\overline{RD}$ ↑ (Acknowledge) Hold Time	0[b]		0[b]		
43	TdIEI(IEO)	IEI to IEO Delay Time		120[b]		100[b]	
44	TdPC(IEO)	PCLK ↑ to IEO Delay		250[b]		250[a]	
45	TdRDA(INT)	$\overline{RD}$ ↓ to $\overline{INT}$ Inactive Delay		500[b]		500[b]	5
46	TdRD(WRQ)	$\overline{RD}$ ↑ to $\overline{WR}$ ↓ Delay for No Reset	30[b]		15[b]		
47	TdWRQ(RD)	$\overline{WR}$ ↑ to $\overline{RD}$ ↓ Delay for No Reset	30[b]		30[b]		
48	TwRES	$\overline{WR}$ and $\overline{RD}$ Coincident Low for Reset	250[a]		250[a]		
49	Trc	Valid Access Recovery Time	6TcPC +200[b]		6TcPC +130[b]		4

NOTES:
4. Parameter applies only between transactions involving the SCC.
5. Open-drain output, measured with open-drain test load.
6. Parameter is system dependent. For any SCC in the daisy chain, TdIAi(RD) must be greater than the sum of TdPC(IEO) for the highest priority device in the daisy chain, TsIEI(RDA) for the SCC, and TdIEIf(IEO) for each device separating them in the daisy chain.

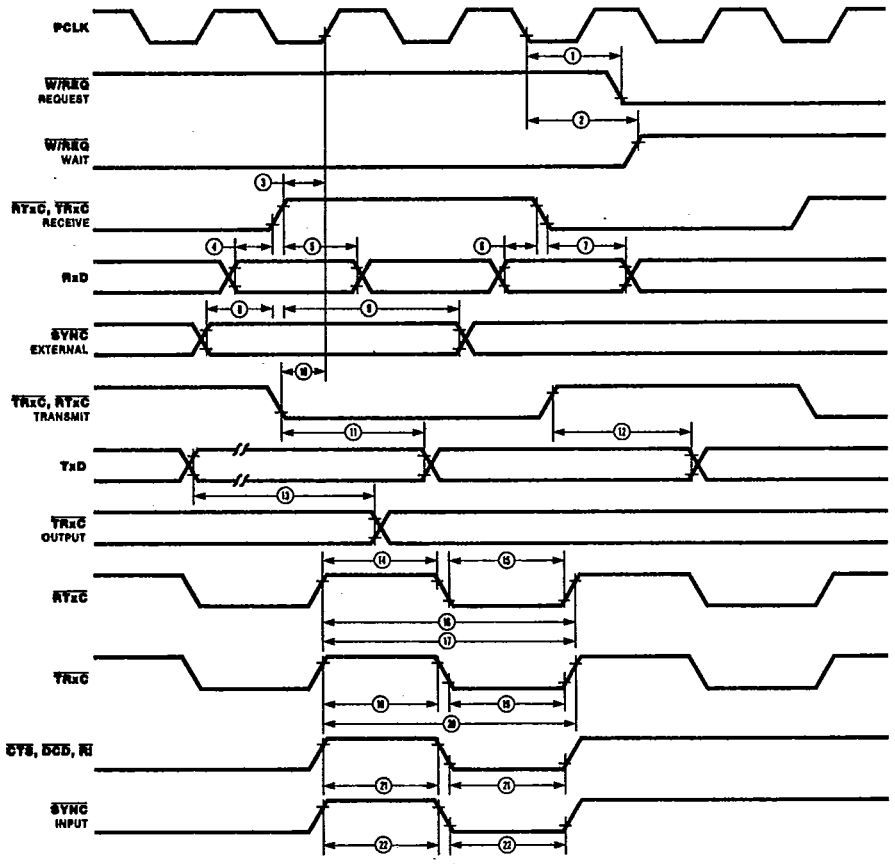
† Units in nanoseconds (ns).

Parameter Test Status:

[a] Tested
[b] Guaranteed
[c] Guaranteed by Characterization/Design

GENERAL TIMING

T-75-37-07



AC CHARACTERISTICS

General Timing

T-75-37-07

Number	Symbol	Parameter	4 MHz Min	4 MHz Max	6 MHz Min	6 MHz Max	Notes†
1	TdPC(REQ)	PCLK ↓ to $\overline{W/REQ}$ Valid Delay		250[b]		250[b]	
2	TdPC(W)	PCLK ↓ to Wait Inactive Delay		350[b]		350[b]	
3	TsRXC(PC)	$\overline{RxC}$ ↑ to PCLK ↑ Setup time (PCLK ÷ 4 case only)	80[a]	TwPCl[b]	70[a]	TwPCl[b]	1,4
4	TsRXD(RXCr)	RxD to $\overline{RxC}$ ↑ Setup Time (X1 Mode)	0[b]		0[b]		1
5	ThRXD(RXCr)	RxD to $\overline{RxC}$ ↑ Hold Time (X1 Mode)	150[b]		150[a]		1
6	TsRXD(RXCf)	RxD to $\overline{RxC}$ ↓ Setup Time (X1 Mode)	0[b]		0[b]		1,5
7	ThRXD(RXCf)	RXD to $\overline{RxC}$ ↓ Hold Time (X1 Mode)	150[b]		150[a]		1,5
8	TsSY(RXC)	$\overline{SYNC}$ to $\overline{RxC}$ ↑ Setup Time	−200[b]		−200[b]		1
9	ThSY(RXC)	$\overline{SYNC}$ to $\overline{RxC}$ ↑ Hold Time	3TcPC +200[b]		3TcPC +200[b]		1
10	TsTXC(PC)	$\overline{TxC}$ ↓ to PCLK ↑ Setup Time	0[a]		0[a]		2,4
11	TdTXCf(TXD)	$\overline{TxC}$ ↓ to TxD Delay (X1 Mode)		300[a]		230[a]	2
12	TdTXCr(TXD)	$\overline{TxC}$ ↑ to TxD Delay (X1 Mode)		300[a]		230[a]	2,5
13	TdTXD(TRX)	TxD to $\overline{TRxC}$ Delay (Send Clock Echo)		200[b]		200[b]	
14	TwRTXh	$\overline{RTxC}$ High Width	180[b]		180[b]		6
15	TwRTXl	$\overline{RTxC}$ Low Width	180[b]		180[b]		6
16	TcRTX	$\overline{RTxC}$ Cycle Time	400[b]		400[b]		6
17	TcRTXX	Crystal Oscillator Period	250[b]	1000[b]	250[b]	1000[b]	3
18	TwTRXh	$\overline{TRxC}$ High Width	180[b]		180[b]		6
19	TwTRXl	$\overline{TRxC}$ Low Width	180[b]		180[b]		6
20	TcTRX	$\overline{TRxC}$ Cycle Time	400[b]		400[b]		6
21	TwEXT	$\overline{DCD}$ or $\overline{CTS}$ Pulse Width	200[b]		200[b]		
22	TwSY	$\overline{SYNC}$ Pulse Width	200[b]		200[b]		

NOTES:
1. $\overline{RxC}$ is $\overline{RTxC}$ or $\overline{TRxC}$, whichever is supplying the receive clock.
2. $\overline{TxC}$ is $\overline{TRxC}$ or $\overline{RTxC}$, whichever is supplying the transmit clock.
3. Both $\overline{RTxC}$ and $\overline{SYNC}$ have 30 pf capacitors to ground connected to them.
4. Parameter applies only if the data rate is one-fourth the PCLK rate. In all other cases, no phase relationship between $\overline{RxC}$ and PCLK or $\overline{TxC}$ and PCLK is required.
5. Parameter applies only to FM encoding/decoding.
6. Parameter applies only for transmitter and receiver; DPLL and baud rate generator timing requirements are identical to chip PCLK requirements.

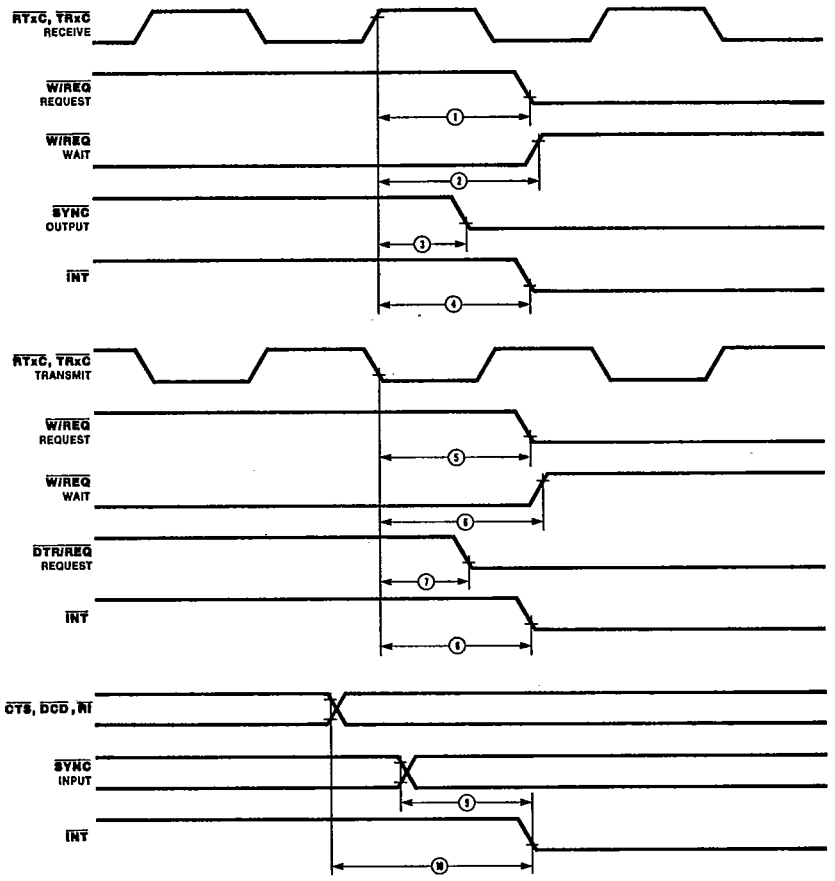
† Units in nanoseconds (ns).

Parameter Test Status:

[a] Tested
[b] Guaranteed
[c] Guaranteed by Characterization/Design

T-75-37-07

SYSTEM TIMING



AC CHARACTERISTICS

System Timing

T-75-37-07

Number	Symbol	Parameter	4 MHz Min	4 MHz Max	6 MHz Min	6 MHz Max	Notes†
1	TdRXC(REQ)	$\overline{RxC}$ ↑ to W/$\overline{REQ}$ Valid Delay	8[b]	12[b]	8[b]	12[b]	2
2	TdRXC(W)	$\overline{RxC}$ ↑ to Wait Inactive Delay	8[b]	12[b]	8[b]	12[b]	1,2
3	TdRXC(SY)	$\overline{RxC}$ ↑ to $\overline{SYNC}$ Valid Delay	4[b]	7[b]	4[b]	7[b]	2
4	TdRXC(INT)	$\overline{RxC}$ ↑ to $\overline{INT}$ Valid Delay	10[b]	16[b]	10[b]	16[b]	1,2
5	TdTXC(REQ)	$\overline{TxC}$ ↓ to W/$\overline{REQ}$ Valid Delay	5[b]	8[b]	5[b]	8[b]	3
6	TdTXC(W)	$\overline{TxC}$ ↓ to Wait Inactive Delay	5[b]	8[b]	5[b]	8[b]	1,3
7	TdTXC(DRQ)	$\overline{TxC}$ ↓ to $\overline{DTR}$/$\overline{REQ}$ Valid Delay	4[b]	7[b]	4[b]	7[b]	3
8	TdTXC(INT)	$\overline{TxC}$ ↓ to $\overline{INT}$ Valid Delay	6[b]	10[b]	6[b]	10[b]	1,3
9	TdSY(INT)	$\overline{SYNC}$ Transition to $\overline{INT}$ Valid Delay	2[b]	6[b]	2[b]	6[b]	1
10	TdEXT(INT)	$\overline{DCD}$ or $\overline{CTS}$ Transition to $\overline{INT}$ Valid Delay	2[b]	6[b]	2[b]	6[b]	1

NOTES:

1. Open-drain output, measured with open-drain test load.
2. $\overline{RxC}$ is $\overline{RTxC}$ or $\overline{TRxC}$, whichever is supplying the receive clock.
3. $\overline{TxC}$ is $\overline{TRxC}$ or $\overline{RTxC}$, whichever is supplying the transmit clock.

† Units equal to TcPC.

Parameter Test Status:

[a] Tested
[b] Guaranteed
[c] Guaranteed by Characterization/Design

PIN DESCRIPTION

T-75-37-07

The following section describes the pin functions of the SCC. Figures 4 and 5 detail the pin functions and assignments.

A/$\overline{B}$. *Channel A/Channel B Select* (input). This signal selects the channel in which the read or write operation occurs.

$\overline{CE}$. *Chip Enable* (input, active Low). This signal selects the SCC for a read or write operation.

$\overline{CTSA}$, $\overline{CTSB}$. *Clear to Send* (inputs, active Low). If these pins are programmed as Auto Enables, a Low on the inputs enables the respective transmitters. If not programmed as Auto Enables, they may be used as general-purpose inputs. Both inputs are Schmitt-trigger buffered to accommodate slow rise-time inputs. The SCC detects pulses on these inputs and can interrupt the CPU on both logic level transitions.

D/$\overline{C}$. *Data/Control Select* (input). This signal defines the type of information transferred to or from the SCC. A High means data is transferred; a Low indicates a command.

$\overline{DCDA}$, $\overline{DCDB}$. *Data Carrier Detect* (inputs, active Low). These pins function as receiver enables if they are programmed for Auto Enables; otherwise they may be used as general-purpose input pins. Both pins are Schmitt-trigger buffered to accommodate slow rise-time signals. The SCC detects pulses on these pins and can interrupt the CPU on both logic level transitions.

D_0-D_7. *Data Bus* (bidirectional, 3-state). These lines carry data and commands to and from the SCC.

$\overline{DTR/REQA}$, $\overline{DTR/REQB}$. *Data Terminal Ready/Request* (outputs, active Low). These outputs follow the state programmed into the DTR bit. They can also be used as general-purpose outputs or as Request lines for a DMA controller.

IEI. *Interrupt Enable In* (input, active High). IEI is used with IEO to form an interrupt daisy chain when there is more than one interrupt-driven device. A High IEI indicates that no other higher priority device has an interrupt under service or is requesting an interrupt.

IEO. *Interrupt Enable Out* (output, active High). IEO is High only if IEI is High and the CPU is not servicing an SCC interrupt or the SCC is not requesting an interrupt (Interrupt Acknowledge cycle only). IEO is connected to the next lower priority device's IEI input and thus inhibits interrupts from lower priority devices.

$\overline{INT}$. *Interrupt Request* (output, open-drain, active Low). This signal is activated when the SCC requests an interrupt.

$\overline{INTACK}$. *Interrupt Acknowledge* (input, active Low). This signal indicates an active Interrupt Acknowledge cycle. During this cycle, the SCC interrupt daisy chain settles. When $\overline{RD}$ becomes active, the SCC places an interrupt vector on the data bus (if IEI is High). $\overline{INTACK}$ is latched by the rising edge of PCLK.

PCLK. *Clock* (input). This is the master SCC clock used to synchronize internal signals. PCLK is a TTL level signal.

$\overline{RD}$. *Read* (input, active Low). This signal indicates a read operation and when the SCC is selected, enables the SCC's bus drivers. During the Interrupt Acknowledge cycle, this signal gates the interrupt vector onto the bus if the SCC is the highest priority device requesting an interrupt.

RxDA, RxDB. *Receive Data* (inputs, active High). These input signals receive serial data at standard TTL levels.

$\overline{RTxCA}$, $\overline{RTxCB}$. *Receive/Transmit Clocks* (inputs, active Low). These pins can be programmed in several different modes of operation. In each channel, $\overline{RTxC}$ may supply the receive clock, the transmit clock, the clock for the baud rate generator, or the clock for the Digital Phase-Locked Loop. These pins can also be programmed for use with the respective $\overline{SYNC}$ pins as a crystal oscillator. The receive clock may be 1, 16, 32, or 64 times the data rate in Asynchronous modes.

$\overline{RTSA}$, $\overline{RTSB}$. *Request To Send* (outputs, active Low). When the Request To Send (RTS) bit in Write Register 5 is set, the $\overline{RTS}$ signal goes Low. When the RTS bit is reset in the Asynchronous mode and Auto Enable is on, the signal goes High after the transmitter is empty. In Synchronous mode or in Asynchronous mode with Auto Enable off, the $\overline{RTS}$ pin strictly follows the state of the RTS bit. Both pins can be used as general-purpose outputs.

$\overline{SYNCA}$, $\overline{SYNCB}$. *Synchronization* (inputs or outputs, active Low). These pins can act either as inputs, outputs, or part of the crystal oscillator circuit. In the Asynchronous Receive mode (crystal oscillator option not selected), these pins are inputs similar to $\overline{CTS}$ and $\overline{DCD}$. In this mode, transitions on these lines affect the state of the Synchronous/Hunt status bits in Read Register 0 but have no other function.

In External Synchronization mode with the crystal oscillator not selected, these lines also act as inputs. In this mode, $\overline{SYNC}$ must be driven Low two receive clock cycles after the last bit in the synchronous character is received. Character assembly begins on the rising edge of the receive clock immediately preceding the activation of $\overline{SYNC}$.

In the Internal Synchronization mode (Monosync and Bisync) with the crystal oscillator not selected, these pins act as outputs and are active only during the part of the receive clock cycle in which synchronous characters are recognized. The synchronous condition is not latched, so these outputs are active each time a synchronization pattern is recognized (regardless of character boundaries). In SDLC mode, these pins act as outputs and are valid on receipt of a flag.

TxDA, TxDB. *Transmit Data* (outputs, active High). These output signals transmit serial data at standard TTL levels.

$\overline{TRxCA}$, $\overline{TRxCB}$. *Transmit/Receive Clocks* (inputs or outputs, active Low). These pins can be programmed in several different modes of operation. $\overline{TRxC}$ may supply the receive clock or the transmit clock in the input mode or supply the output of the Digital Phase-Locked Loop, the crystal oscillator, the baud rate generator, or the transmit clock in the output mode.

$\overline{WR}$. *Write* (input, active Low). When the SCC is selected, this signal indicates a write operation. The coincidence of $\overline{RD}$ and $\overline{WR}$ is interpreted as a reset.

$\overline{W/REQA}$, $\overline{W/REQB}$. *Wait/Request* (outputs, open-drain when programmed for a Wait function, driven High or Low when programmed for a Request function). These dual-purpose outputs may be programmed as Request lines for a DMA controller or as Wait lines to synchronize the CPU to the SCC data rate. The reset state is Wait.

PACKAGE PINOUTS

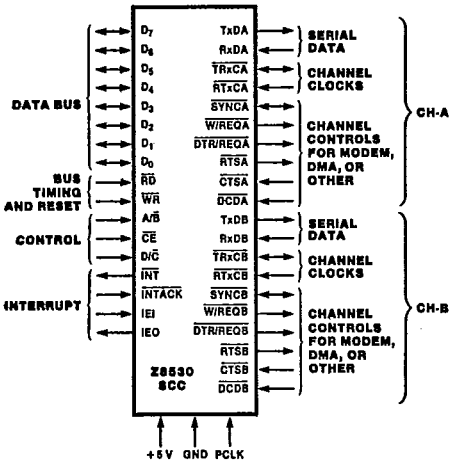


Figure 4. Pin Functions

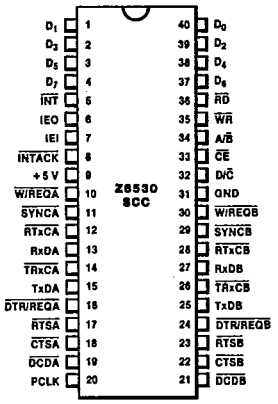


Figure 5. 40-pin Dual-In-Line Package (DIP), Pin Assignments

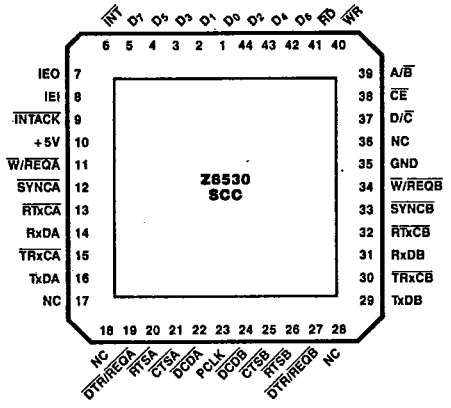


Figure 6. 44-pin Chip Carrier, Pin Assignments

MIL-STD-883 MILITARY PROCESSED PRODUCT

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- Mil-Std-883 establishes uniform methods and procedures for testing microelectronic devices to insure the electrical, mechanical, and environmental integrity and reliability that is required for military applications.
- Mil-Std-883 Class B is the industry standard product assurance level for military ground and aircraft application.
- The total reliability of a system depends upon tests that are designed to stress specific quality and reliability concerns that affect microelectronic products.
- The following tables detail the 100% screening and electrical tests, sample electrical tests, and Qualification/ Quality Conformance testing required.

Zilog Military Product Flow

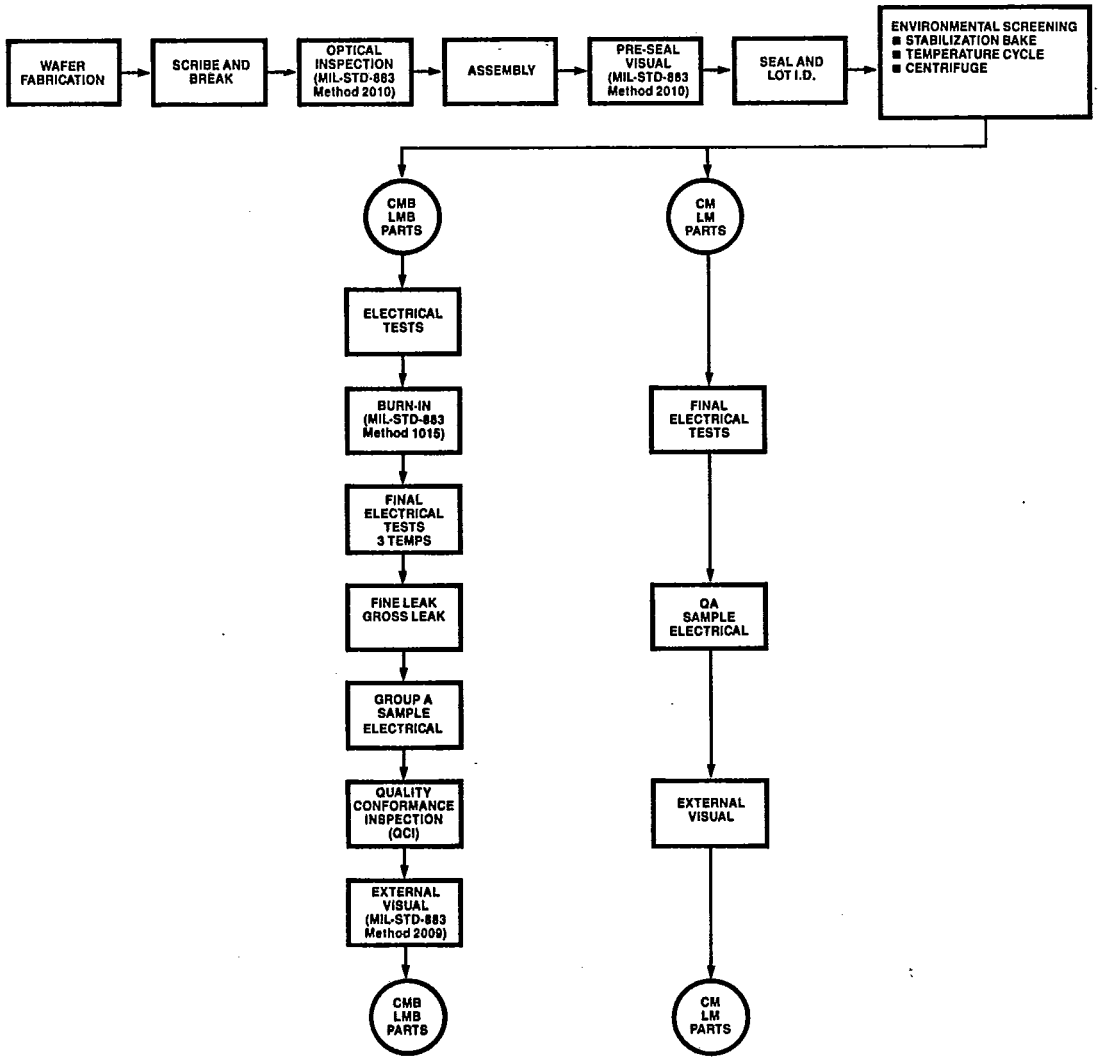

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Table I

MIL-STD-883 Class B Screening Requirements
Method 5004

Test	Mil-Std-883 Method	Test Condition	Requirement
Internal Visual	2010	Condition B	100%
Stabilization Bake	1008	Condition C	100%
Temperature Cycle	1010	Condition C	100%
Constant Acceleration (Centrifuge)	2001	Condition E or D(Note 1), Y_1 Axis Only	100%
Initial Electrical Tests		Zilog Military Electrical Specification Static/DC T_C = +25°C	100%
Burn-In	1015	Condition D(Note 2), 160 hours, T_A = +125°C	100%
Interim Electrical Tests		Zilog Military Electrical Specification Static/DC T_C = +25°C	100%
PDA Calculation		PDA = 5%	100%
Final Electrical Tests		Zilog Military Electrical Specification Static/DC T_C = +125°C, −55°C Functional, Switching/AC T_C = +25°C	100%
Fine Leak	1014	Condition A_2	100%
Gross Leak	1014	Condition C	100%
Quality Conformance Inspection (QCI)			
Group A Each Inspection Lot	5005	(See Table II)	Sample
Group B Every Week	5005	(See Table III)	Sample
Group C Periodically (Note 3)	5005	(See Table IV)	Sample
Group D Periodically (Note 3)	5005	(See Table V)	Sample
External Visual	2009		100%
QA—Ship			100%

NOTES:
1. Applies to larger packages which have an inner seal or cavity perimeter of two inches or more in total length or have a package mass of ≥5 grams.
2. In process of fully implementing of Condition D Burn-In Circuits. Contact factory for copy of specific burn-in circuit available.
3. Performed periodically as required by Mil-Std-883, paragraph 1.2.1 b(17).

Table II Group A

Sample Electrical Tests
MIL-STD-883 Method 5005

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Subgroup	Tests	Temperature (T_C)	LTPD Max Accept = 2
Subgroup 1	Static/DC	+25°C	2
Subgroup 2	Static/DC	+125°C	3
Subgroup 3	Static/DC	−55°C	5
Subgroup 7	Functional	+25°C	2
Subgroup 8	Functional	−55°C and +125°C	5
Subgroup 9	Switching/AC	+25°C	2
Subgroup 10	Switching/AC	+125°C	3
Subgroup 11	Switching/AC	−55°C	5

NOTES:
- The specific parameters to be included for tests in each subgroup shall be as specified in the applicable detail electrical specification. Where no parameters have been identified in a particular subgroup or test within a subgroup, no Group A testing is required for that subgroup or test.
- A single sample may be used for all subgroup testing. Where required size exceeds the lot size, 100% inspection shall be allowed.
- Group A testing by subgroup or within subgroups may be performed in any sequence unless otherwise specified.

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Table III Group B

Sample Test Performed Every Week to Test Construction and Insure Integrity of Assembly Process. MIL-STD-883 Method 5005

Subgroup	Mil-Std-883 Method	Test Condition	Quantity or LTPD/Max Accept
Subgroup 1			
Physical Dimensions	2016		2/0
Subgroup 2			
Resistance to Solvents	2015		4/0
Subgroup 3			
Solderability	2003	Solder Temperature +245°C ± 5°C	15(Note 1)
Subgroup 4			
Internal Visual and Mechanical	2014		1/0
Subgroup 5			
Bond Strength	2011	C	15(Note 2)
Subgroup 6(Note 3)			
Internal Water Vapor Content	1018	1000 ppm. maximum at +100°C	3/0 or 5/1
Subgroup 7(Note 4)			
Seal	1014		5
7a) Fine Leak		7a) A_2	
7b) Gross Leak		7b) C	
Subgroup 8(Note 5)			
Electrostatic Discharge Sensitivity	3015	Zilog Military Electrical Specification Static/DC T_C = +25°C A = 20-2000V B = >2000V Zilog Military Electrical Specification Static/DC T_C = +25°C	15/0

NOTES:
1. Number of leads inspected selected from a minimum of 3 devices.
2. Number of bond pulls selected from a minimum of 4 devices.
3. Test applicable only if the package contains a dessicant.
4. Test not required if either 100% or sample seal test is performed between final electrical tests and external visual during Class B screening.
5. Test required for initial qualification and product redesign.

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Table IV Group C

Sample Test Performed Periodically to Verify Integrity of the Die.
MIL-STD-883 Method 5005

Subgroup	Mil-Std-883 Method	Test Condition	Quantity or LTPD/Max Accept
Subgroup 1			
Steady State Operating Life	1005	Condition D(Note 1), 1000 hours at +125°C	5
End Point Electrical Tests		Zilog Military Electrical Specification T_C = +25°C, +125°C, −55°C	
Subgroup 2			
Temperature Cycle	1010	Condition C	
Constant Acceleration (Centrifuge)	2001	Condition E or D(Note 2), Y_1 Axis Only	
Seal	1014		15
2a) Fine Leak		2a) Condition A_2	
2b) Gross Leak		2b) Condition C	
Visual Examination	1010 or 1011		
End Point Electrical Tests		Zilog Military Electrical Specification T_C = +25°C, +125°C, −55°C	

NOTE:
1. In process of fully implementing Condition D Burn-In Circuits. Contact factory for copy of specific burn-in circuit available.
2. Applies to larger packages which have an inner seal or cavity perimeter of two inches or more in total length or have a package mass of ≥5 grams.

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Table V Group D

Sample Test Performed Periodically to Insure Integrity of the Package.
MIL-STD-883 Method 5005

Subgroup	Mil-Std-883 Method	Test Condition	Quantity or LTPD/Max Accept
Subgroup 1			
Physical Dimensions	2016		15
Subgroup 2			
Lead Integrity	2004	Condition B_2 or D(Note 1)	15
Subgroup 3			
Thermal Shock	1011	Condition B minimum, 15 cycles minimum	
Temperature Cycling	1010	Condition C, 100 cycles minimum	15
Moisture Resistance	1004		
Seal	1014		
3a) Fine Leak		3a) Condition A_2	
3b) Gross Leak		3b) Condition C	
Visual Examination	1004 or 1010		
End Point Electrical Tests		Zilog Military Electrical Specification T_C = +25°C, +125°C, −55°C	
Subgroup 4			
Mechanical Shock	2002	Condition B minimum	
Vibration Variable Frequency	2007	Condition A minimum	
Constant Acceleration (Centrifuge)	2001	Condition E or D(Note 2), Y_1 Axis Only	15
Seal	1014		
4a) Fine Leak		4a) Condition A_2	
4b) Gross Leak		4b) Condition C	
Visual Examination	1010 or 1011		
End Point Electrical Tests		Zilog Military Electrical Specification T_C = +25°C, +125°C, −55°C	
Subgroup 5			
Salt Atmosphere	1009	Condition A minimum	
Seal	1014		15
5a) Fine Leak		5a) Condition A_2	
5b) Gross Leak		5b) Condition C	
Visual Examination	1009		
Subgroup 6			
Internal Water Vapor Content	1018	5,000 ppm. maximum water content at +100°C	3/0 or 5/1
Subgroup 7(Note 3)			
Adhesion of Lead Finish	2025		15(Note 4)
Subgroup 8(Note 5)			
Lid Torque	2024		5/0

NOTES:
1. Lead Integrity Condition D for leadless chip carriers.
2. Applies to larger packages which have an inner seal or cavity perimeter of two inches or more in total length or have a package mass of ≥5 grams.
3. Not applicable to leadless chip carriers.
4. LTPD based on number of leads.
5. Not applicable for solder seal packages.

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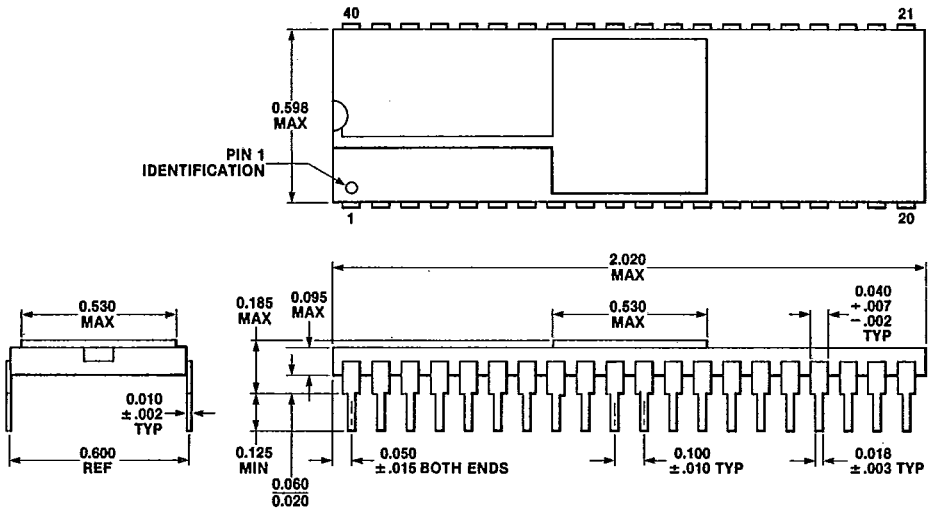
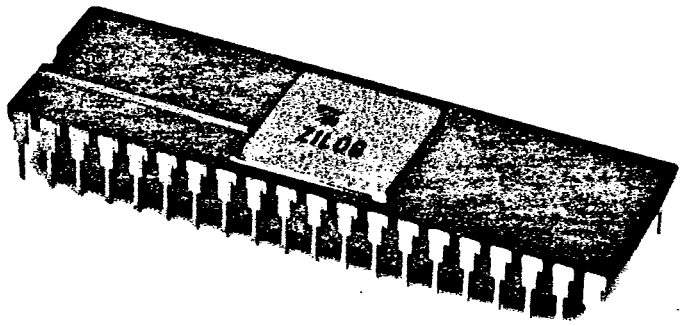
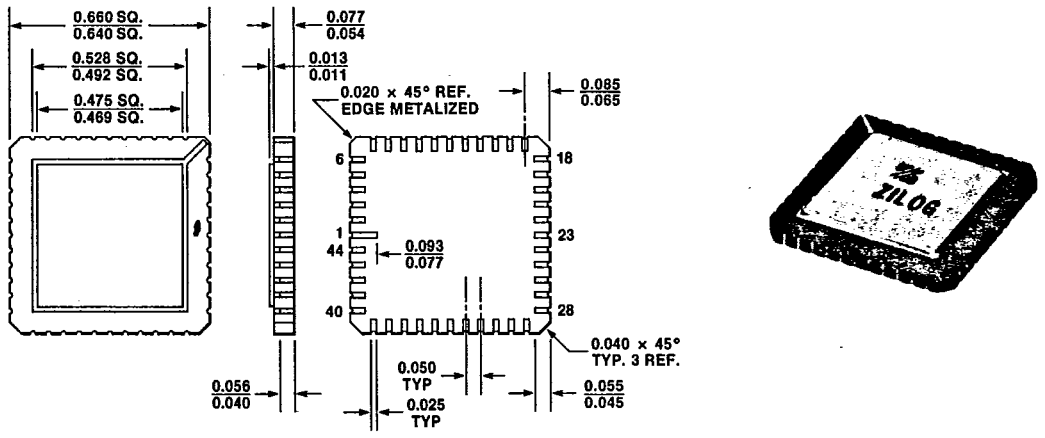
PACKAGE INFORMATION





40-Pin Ceramic Dual In-line Package (DIP)



44-Pin Ceramic Leadless Chip Carrier (LCC)

ZILOG ORDERING INFORMATION

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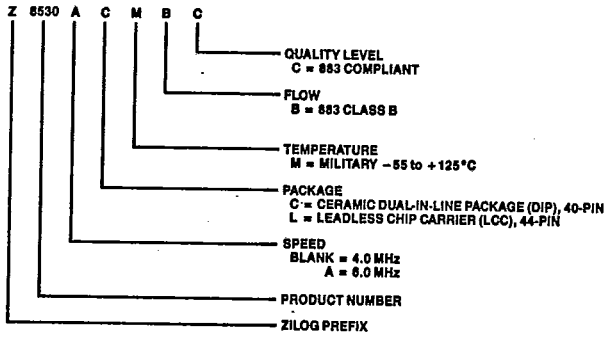

AVAILABLE MILITARY PRODUCTS

Z8530 SCC, 4.0 MHz

40-pin DIP	44-pin LCC
Z8530 CM	Z8530 LM
Z8530 CMBC	Z8530 LMBC

Z8530A SCC, 6.0 MHz

40-pin DIP	44-pin LCC
Z8530A CM	Z8530A LM
Z8530A CMBC	Z8530A LMBC